

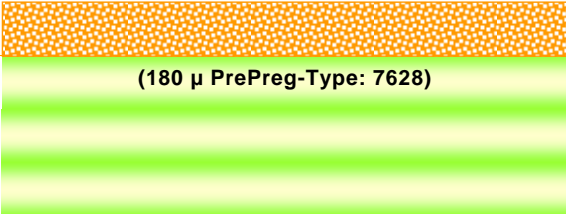
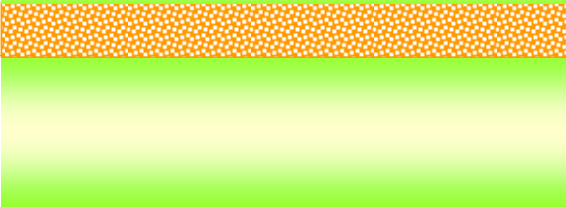
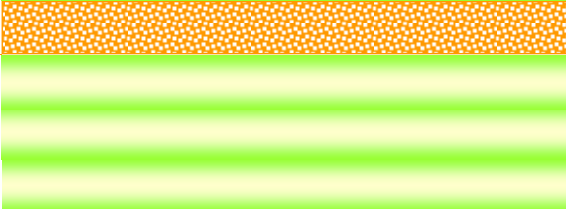

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

04 186 FR4 105 L36.105 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_186_FR4_105_L36.105_p18

Layers	in μ	Material	Build-Up	Assembly	
Layer-1	105 μ	Copper		A1	
	180 μ	Prepreg			
	180 μ	Prepreg			
	180 μ	Prepreg			
Layer-2	105 μ	Copper			B
	360 μ	L-FR4			
Layer-3	105 μ	Copper			
	180 μ	Prepreg			
	180 μ	Prepreg			
	180 μ	Prepreg			
Layer-99	105 μ	Copper			

© Copyright by Printed Circuit Boards GmbH